

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning at page 2, line 32 with the following rewritten paragraph:

-- A second aspect of the present invention provides a process for providing the device of the present invention, wherein gas plasma is deposited under the following conditions:

- a.) a discharge power of up to 5000 W, for example up to 500 W;
b.) an exposure duration of up to 1000 s, for example up to 100 s;
c.) a plasma gas flow of up to 10000 cm³/min, for example up to 100
cm³/min;
d.) a pressure of up to 1 bar, for example up to 0.001-50 mbar; and
e.) a frequency covering DC, AC, RF, and the MW ranges, for example a
frequency between 2-60 Mhz,

wherein the discharge power is pulsed to the plasma, the pulse discharges
being separated by up to 100 s.--
